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(a) an organic layer on a surface of the substrate which comprises a pattern of metal lines on the substrate and an organic dielectric on the substrate surface between the metal lines; and

(b) an inorganic layer on the organic layer which comprises an inorganic dielectric selected from the group consisting of hydrogensiloxanes, inorganic hydrogensilsesquioxanes and combinations thereof, having metal filled vias therethrough which connect to the metal lines of the organic layer; and wherein the hydrogensiloxanes have the formula $[(\text{HSiO}_{1.5})_x\text{O}_y]_n$, and the hydrogensilsesquioxanes have the formula $(\text{HSiO}_{1.5})_n$, wherein x = about 6 to about 20, y =1 to about 3, and n =1 to about 4,000.

Sub 027

C²

29. (Twice Amended) A dielectric coated substrate which comprises:

(a) a first dielectric composition film on a surface of a substrate; and

(b) a second dielectric composition film on the first dielectric composition film; wherein the first dielectric composition and the second dielectric composition have substantially different etch resistance; wherein either the first dielectric composition film is organic and the second dielectric composition film is inorganic; or the first dielectric composition film is inorganic and the second dielectric composition film is organic; and wherein the inorganic dielectric composition film comprises an inorganic dielectric selected from the group consisting of hydrogensiloxanes, inorganic hydrogensilsesquioxanes and combinations thereof; and wherein the hydrogensiloxanes have the formula $[(\text{HSiO}_{1.5})_x\text{O}_y]_n$, and the hydrogensilsesquioxanes have the formula $(\text{HSiO}_{1.5})_n$, wherein x = about 6 to about 20, y =1 to about 3, and n =1 to about 4,000.

Cancel claims 32 and 33.